



FORM PTO-1449 (SUBSTITUTE)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEINFORMATION DISCLOSURE
STATEMENT BY APPLICANT
(37 CFR 1.98(b))

Attorney Docket No.:

P2000,0361

Applic. No.

10/609,464

Applicant

Wolfgang Dickenscheid et al.

Filing Date

June 27, 2003

Group Art Unit

U.S. PATENT DOCUMENTS

EXAMINER INITIALS		PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A						
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		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

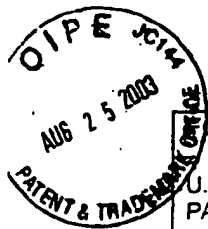
	O	J. Tony Pan et al.: "Planarization and Integration of Shallow Trench Isolation", 1998 <i>Proceedings of the Fifteenth International VLSI Multilevel Interconnection Conference (VMIC)</i> , Santa Clara, CA, June 16-18, 1998, pp. 467-472
	P	George Y. Liu et al.: "Chip-Level CMP Modeling and Smart Dummy for HDP and Conformal CVD Films", 1999 <i>Proceedings of the Fourth International Chemical-Mechanical Planarization for ULSI Multilevel Interconnection Conference (CMP-MIC)</i> , Santa Clara, CA, February 11-12, 1999, pp. 120-127

EXAMINER

DATE CONSIDERED

4/2/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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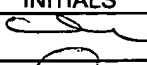


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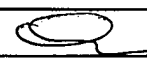
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

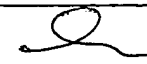



	O	Valeriy Sukharev: "Addressing the pattern density effects in deposition, etch and CMP by means of simulations", 2001 <i>Proceedings of the Sixth International Chemical-Mechanical Planarization for ULSI Multilevel Interconnection Conference (CMP-MIC)</i> , Santa Clara, CA, March 7-9, 2001, pp. 403-413
	P	Carsten Schmitz et al.: "CMPSIM - Ein Simulator für den Planarisierungsprozess auf Layout Ebene" [CMPSIM - a simulator for the planarization process on the layout level], <i>internal memo, Infineon Technologies AG, München, November 26, 1999, pp. 1-17</i>
EXAMINER		
DATE CONSIDERED		2/2/08

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EXAMINER INITIALS	PATENT NO.	DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE
	A	5,599,423	2/4/97	Parker et al.		
	B	6,159,075	12/12/00	Zhang		
	C	6,057,068	5/2/00	Raeder et al.		
	D					
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DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB CLASS	TRANSL. YES NO		
 J	99/25520	5/27/99	WIPO				
	K						
	L						
	M						
	N						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)	
	Smith, T.H.: "A CMP Model Combining Density and Time Dependencies", Proc.CMP-MIC, 1999, 8 pages
	Ouma, D. et al.: "An Integrated Characterization and Modeling Methodology for CMP Dielectric Planarization", Massachusetts Institute of Technology, 3 pages
EXAMINER	 <div style="display: inline-block; vertical-align: top; margin-left: 20px;"> DATE CONSIDERED  </div>

6-27/2003

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		Stine, B. et al.: "A Closed-Form Analytic Model for ILD Thickness Variation in CMP Processes", Proc.CMP-MIC, 1997, pp. 1-7					
EXAMINER 				DATE CONSIDERED 2/2/05			